

# R1272S032A033-0500EV

# 34 V Input Synchronous Step-down DC / DC Controller Evaluation Board

NO.EEV-351-032A033-0500-220218

R1272S032A033-0500EV is the evaluation board for R1272 which has the below features, benefits and specifications.

#### **OUTLINE**

The R1272S is a step-down DC/DC controller which can generate an output voltage of 0.7 V to 5.3 V by driving external high- / low-side NMOSs. By the adoption of a unique current mode PWM architecture without an external current sense resistor, the R1272S can make up a stable DC/DC converter with high-efficiency even if adding low Ron MOSFETs and a low DCR inductor externally. And, by the frequency characteristics optimization with using external phase compensation capacitor, the R1272S can achieve a high-speed response to variations of input voltage and load current. The user-settable oscillation frequency is adjustable over a range of 250 kHz to 1 MHz<sup>(1)</sup> by external resistors, and also can be synchronized to an external clock. Output Voltage Control Methods have three operating modes: Forced PWM mode, PLL\_PWM mode, and PWM/VFM Auto-switching mode. These modes are selectable according to conditions of the MODE pin. Especially, the PWM/VFM Auto-switching mode can improve efficiency under light load conditions.

The R1272S can minimize the output voltage drop caused by an input voltage drop at cranking, with reducing the operating frequency (the lowest possible limit is a quarter of the frequency) so that the off-duty is reduced. Protection functions include a current limit function, an UVLO (Under Voltage Lock Out) function, an OVP (Over Voltage Protection) function, a soft-start function, a low-inductor current shutdown function, and so on. Also, a power good function provides the status of output with using a power good (PGOOD) pin.

For EMI reduction, SSCG (Spread-Spectrum Clock Generator) for diffused oscillation frequency at the PWM operation is optionally available.

#### **FEATURES**

•	Operating Voltage (Maximum Rating)	4.0 V to 34 V (36 V)
•	Operating Temperature Range ······	-40°C ≤ Ta ≤ 105°C
		(Usable in high-temperature environment)
•	Start-up Voltage ·····	4.5 V
•	Output Voltage ·····	3.3 V
•	Feedback Voltage Tolerance · · · · · · · · · · · · · · · · · · ·	0.64 V ± 1%
•	Consumption Current at No Load (at VFM mode) ·······	Typ.15 μA
•	Adjustable Oscillation Frequency	500 kHz
•	Synchronizable Clock Frequency	250 kHz to 1 MHz
•	Spreading Rate for SSCG ······	Typ. ±3.6%
•	Minimum On-Time · · · · · · · · · · · · · · · · · · ·	Typ.100 ns
•	Minimum Off-Time · · · · · · · · · · · · · · · · · · ·	Typ.120 ns (at regulation mode)
		At dropout, actual minimum off-time is reduced.
•	Adjustable Soft-start Time (1)	Typ.500 μs
•	Pre-bias Start-up	

(1) 500 μs (Typ.) as a lower limit with using an external capacitor. Otherwise, available the tracking function through the application of an external voltage.

NO.EEV-351-032A033-0500-220218

Anti-phase Clock Output

• Thermal Shutdown Function · · · · · Tj = 160°C (Typ.)

• Under Voltage Lockout (UVLO) Function------ Typ. 3.3 V

• Over Voltage Detection (OVD) Function ······ FB pin voltage (V<sub>FB</sub>) + 10% (Typ.) Detection/Release Hysteresis ····· FB pin voltage (V<sub>FB</sub>) x 3% (Typ.)

Under Voltage Detection (UVD) Function FB pin voltage (V<sub>FB</sub>) - 10% (Typ.)
 Detection/Release Hysteresis FB pin voltage (V<sub>FB</sub>) x 3% (Typ.)
 Over-current Protection Hiccup-mode / Latch mode

Power Good Output · · · · · NMOS Open-drain Output

• Package · · · · · HSOP-18

 For more details on R1272 IC, please refer to https://www.nisshinbo-microdevices.co.jp/en/pdf/datasheet/r1272-ea.pdf.

## PART NUMBER INFORMATION

Product Name	Package
R1272S032A033-0500	HSOP-18

03: Combination of processing and function.

Over Current Protection	SSCG
Latch mode	Enable

2: 70 mV, Set Voltage for Current Limit Threshold (Typ.)

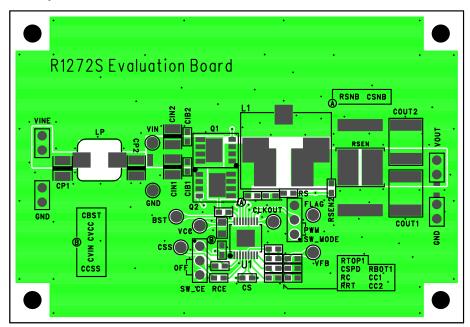
A: Fixed

033: 3.3 V, Output Voltage

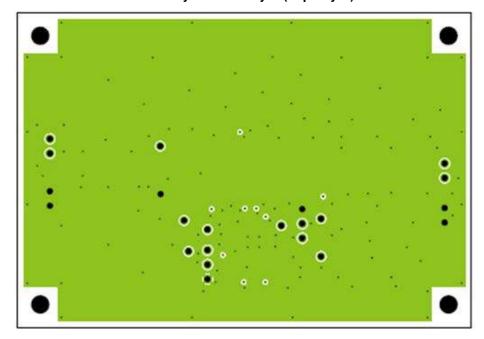
0500: 500 kHz, Frequency

# **PCB LAYOUT**

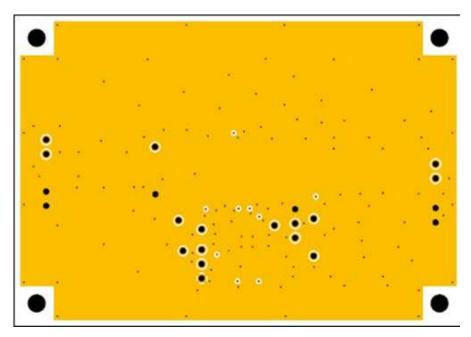
# R1272SxxxA PCB Layouts



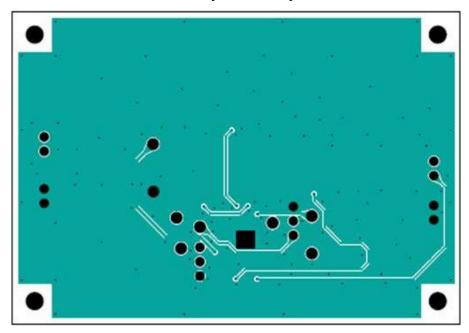
PCB Layout - 1<sup>st</sup> Layer (Top Layer)



PCB Layout - 2<sup>nd</sup> Layer

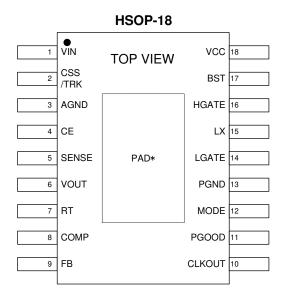


PCB Layout - 3<sup>rd</sup> Layer



PCB Layout – 4<sup>th</sup> Layer (Bottom Layer) R1272SxxxA

# **PIN DESCRIPTIONS**



## **HSOP-18 Pin Description**

Pin No.	Pin Name	Description
1	VIN	Power supply pin
2	CSS/TRK	Soft-start adjustment pin
3	AGND	Analog GND pin
4	CE	Chip enable pin (Active "H")
5	SENSE	Sense pin for inductor current
6	VOUT	Output voltage feedback input pin
7	RT	Oscillation adjustment pin
8	COMP	Capacitor connecting pin for phase compensation of error amplifier
9	FB	Feedback input pin to the error amplifier
10	CLKOUT	Clock output pin
11	PGOOD	Power-good output pin
12	MODE	Mode-set input pin
13	PGND	Power GND pin
14	LGATE	L-side FET control pin
15	LX	Switchingpin
16	HGATE	H-side FET control pin
17	BST	Boostrap pin
18	VCC	VCC output pin

<sup>\*</sup> The tab on the bottom of the package must be electrically connected to GND (substrate level) when mounted on the board.

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Item	Rating	Unit
V <sub>IN</sub>	VIN pin voltage	-0.3 to 36	V
V <sub>CE</sub>	CE pin voltage	-0.3 to 36	V
V <sub>CSS</sub> /V <sub>TRK</sub>	CSS/TRK pin voltage	-0.3 to 3	V
Vout	VOUTpin voltage	-0.3 to 6	V
V <sub>SENSE</sub>	SENSEpin voltage	-0.3 to 6	V
$V_{RT}$	RT pin voltage	-0.3 to 3	V
V <sub>COMP</sub>	COMP pin voltage <sup>(1)</sup>	-0.3 to 6	V
V <sub>FB</sub>	FB pin voltage	-0.3 to 3	V
V	VCC pin voltage	-0.3 to 6	V
$V_{CC}$	Output current for VCC pin	Internally limited	mA
V <sub>BST</sub>	BST pin voltage	LX-0.3 to LX+6	V
VHGATE	HGATE pin voltage	LX-0.3 to BST	V
V <sub>LX</sub>	LX pin voltage <sup>(2)</sup>	-0.3 to 36	V
V <sub>LGATE</sub>	LGATE pin voltage <sup>(1)</sup>	-0.3 to 6	V
V <sub>MODE</sub>	MODE pin voltage	-0.3 to 6	V
V <sub>PGOOD</sub>	PGOOD pin voltage	-0.3 to 6	V
V <sub>CLKOUT</sub>	CLKOUT pin voltage <sup>(1)</sup>	-0.3 to 6	V
PD	Power Dissipation <sup>(3)</sup> (HSOP-18, JEDEC STD.51-7 Test Land Pattern)	3100	mW
Tj	Junction Temperature	-40 to 125	°C
Tstg	Storage Temperature Range	-55 to 125	°C

## ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating	Unit
$V_{IN}$	Input Voltage	4.0 to 34	V
Ta	Operating Temperature Range	-40 to 105	°C
Vout	Output Voltage Range	0.7 to 5.3	V

#### **RECOMMENDED OPERATING CONDITIONS**

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

 $<sup>^{(1)}</sup>$  The pin voltage must be prevented from exceeding  $V_{\text{CC}}$  +0.3V.

 $<sup>^{(2)}</sup>$  The pin voltage must be prevented from exceeding  $V_{\text{IN}}$  +0.3V.

<sup>(3)</sup> Refer to POWER DISSIPATION for detailed information.

## **ELECTRICAL CHARACTERISTICS**

 $V_{\text{IN}}$  = 12 V, CE =  $V_{\text{IN}}$ , unless otherwise specified.

The specifications surrounded by are guaranteed by design engineering at  $-40^{\circ}\text{C} \le \text{Ta} \le 105^{\circ}\text{C}$ .

R1272SxxxA (Ta = 25°C)

Symbol	Ite	m	Conditions	Min.	Тур.	Max.	Unit
VSTART	Start-up Voltage					4.5	V
Vcc	VCC Pin Voltage (VCC-AGND)		V <sub>FB</sub> = 0.672 V	4.9	5.1	5.3	V
ISTANDBY	Standby Current	Ī	V <sub>IN</sub> = 34 V, CE = 0 V		3	20	μΑ
I <sub>VIN1</sub>	VIN Consumption Current 1 at Switching Stop in PWM mode	R1272S0xx	V <sub>FB</sub> = 0.672 V, MODE = 5 V, V <sub>OUT</sub> = SENSE = LX = 5 V		1.0	1.3	mA
Ivin2	VIN Consumption Current 2 at Switching Stop in VFM mode	R1272S0xx	V <sub>FB</sub> = 0.672 V, MODE = 0 V V <sub>OUT</sub> = SENSE = LX = 5 V		15	75	μА
V <sub>UVLO2</sub>	VCC Pin Voltage Standby Current VIN Consumption Current 1 at Switching Stop in PWM mode VIN Consumption Current 2 at Switching Stop in VFM mode  UVLO Threshold  FB Voltage Accur Oscillation Freque Minimum OFF Time Minimum ON Time Synchronizing Free Soft-start Time 1 Soft-start Time 2 Charge Current Pin CSS/TRK Pin Vo Soft-start Discharge Resist	d Voltago	V <sub>CC</sub> Rising	3.85	4.0	4.2	٧
V <sub>UVLO1</sub>	TOVEO THIESHOR	i voltage	V <sub>CC</sub> Falling	3.1	3.3	3.4	٧
V	FR Voltage Accuracy		Ta = 25°C	0.6336	0.64	0.6464	V
$V_{FB}$	FB Vollage Acci	ласу	-40°C ≤ Ta ≤ 105°C	0.6272	0.04	0.6528	] <b>'</b>
f <sub>OSC0</sub>	Oscillation Frequ	uency 0	RT = 135 kΩ	225	250	275	kHz
f <sub>OSC1</sub>	Oscillation Frequ	uency 1	RT = 32 kΩ	900	1000	1100	kHz
toff	Minimum OFF T	ïme	$V_{IN} = 5 V$ , $V_{OUT} = 5 V$		120	190	ns
ton	Oscillation Frequency 0 Oscillation Frequency 1 Minimum OFF Time Minimum ON Time Synchronizing Frequency				100	120	ns
fsync	Synchronizing F	requency	fosc as the reference	fosc×0.5 250		fosc×1.5	kHz
tss1	Soft-start Time 1		CSS / TRK = OPEN	0.4		0.75	ms
tss2	Soft-start Time 2	2	C <sub>SS</sub> = 4.7 nF	1.4		2.0	ms
I <sub>TSS</sub>	Charge Current for Soft-start Pin		CSS / TRK = 0 V	1.8	2	2.2	μА
V <sub>SSEND</sub>	Soft-start			V <sub>FB</sub>	V <sub>FB</sub> +0.03	V <sub>FB</sub> +0.06	V
R <sub>DIS_CSS</sub>	CSS/TRK Pin		V <sub>IN</sub> = 4.5 V, CE = 0 V, CSS / TRK = 3 V	2.0	3.0	5.0	kΩ
Ruphgate	On-resistance of Transistor (HGA		(BST – LX) = 5 V, I <sub>HGATE</sub> = -100 mA		2.5	5.0	Ω

 $V_{\text{IN}}$  = 12 V, CE =  $V_{\text{IN}}$ , unless otherwise specified.

The specifications surrounded by are guaranteed by design engineering at  $-40^{\circ}$ C  $\leq$  Ta  $\leq$  105°C.

#### **R1272SxxxA Continued**

 $(Ta = 25^{\circ}C)$ 

Symbol	Item	Conditions	Min.	Тур.	Max.	Unit
RDOWNHGATE	On-resistance of Pull-down Transistor (HGATE Pin)	(BST – LX) = 5 V, I <sub>HGATE</sub> = 100 mA		1.5	3.5	Ω
RUPLGATE	On-resistance of Pull-up Transistor (LGATE Pin)	(VCC - PGND) = 5 V, $I_{LGATE} = -100 \text{ mA}$		4.0	7.0	Ω
RDOWNLGATE	On-resistance of Pull-down Transistor (LGATE Pin)	$(VCC - PGND) = 5 V,$ $I_{LGATE} = 100 \text{ mA}$		1.5	3.5	Ω
	Current Limit Threshold		40	50	60	mV
$V_{ILIMIT}$	Voltage		60	70	80	mV
	(SENSE – VOUT)		90	100	110	mV
	Reverse Current Sense		-35	-25	-15	mV
$V_{IREVLIMIT}$	Threshold	MODE = H / CLK	-45	-35	-25	mV
	(SENSE – VOUT)		-60	-50	-40	mV
V <sub>LXSHORTL</sub>	LX Shot to GND Detector Threshold Voltage (VIN – LX)		0.345	0.43	0.520	V
VLXSHORTH	LX Short to VCC Detector Threshold Voltage (LX – PGND)		0.330	0.43	0.515	V
$V_{CEH}$	CE "High" Input Voltage		1.27			V
V <sub>CEL</sub>	CE "Low" Input Voltage				1.14	V
I <sub>CEH</sub>	CE "High" Input Current	CE = 34 V	0.20		2.45	μΑ
I <sub>CEL</sub>	CE "Low" Input Current	CE = 0 V	-1.00	0	1.00	μΑ
I <sub>FBH</sub>	FB "High" Input Current	V <sub>FB</sub> = 3 V	-0.10		0.10	μΑ
I <sub>FBL</sub>	FB "Low" Input Current	$V_{FB} = 0 V$	-0.10		0.10	μΑ
V <sub>MODEH</sub>	MODE "High" Input Voltage		1.33			V
VMODEL	MODE "Low" Input Voltage				0.74	V
<b>I</b> MODEH	MODE "High" Input Current	MODE = 6 V	1.00		6.60	μΑ
IMODEL	MODE "Low" Input Current	MODE = 0 V	-1.00	0	1.00	μΑ
Vclkouth	CLKOUT Pin "High"	CLKOUT = Hi-z	<u>и 7</u>		Voo	V
V CLKOUTH	Output Voltage	GLNOOT = TII-2	4.7		Vcc	V
Vclkoutl	CLKOUT Pin "Low"	CLKOUT = Hi-z	O		0.1	V
• CLKOUIL	Output Voltage	OLINOUT - TII-Z			V. II	<b>,</b>
T <sub>TSD</sub>	Thermal Shutdown	Ta Rising	150	160		°C
T <sub>TSR</sub>	Threshold Temperature	Ta Falling	125	140		°C

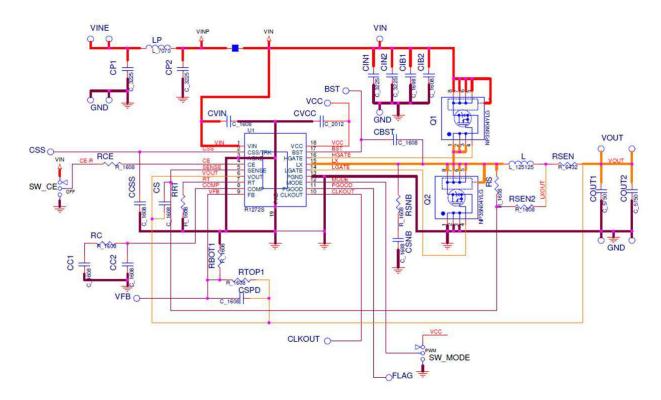
 $V_{\text{IN}}$  = 12 V, CE =  $V_{\text{IN}}$ , unless otherwise specified.

	R1272S
	NO.EEV-351-032A033-0500-220218
The specifications surrounded by are guaranteed by	design engineering at -40°C ≤ Ta ≤ 105°C.
R1272SxxxA Continued	(Ta = 25°C)

	· · · · · · · · · · · · · · · · · · ·				(.∝	_0 0,
Symbol	Item	Conditions	Min	Тур	Max.	Unit
V <sub>PGOODOFF</sub>	PGOOD Pin "OFF" Voltage	V <sub>IN</sub> = 4.0 V, PGOOD = 1 mA		0.26	0.54	V
IPGOODOFF	PGOOD Pin "OFF" Current	V <sub>IN</sub> = 34 V, CE = 0 V, PGOOD = 6 V	-0.10	0	0.10	μΑ
V <sub>FBOVD1</sub>	FB Pin OVD Threshold Voltage	V <sub>FB</sub> Rising	0.680	V <sub>FB</sub> ×1.10	0.740	V
V <sub>FBOVD2</sub>	FB FIII OVD TIII esiloid Voitage	V <sub>FB</sub> Falling	0.664	V <sub>FB</sub> ×1.07	0.712	V
V <sub>FBUVD1</sub>	FB Pin UVD Threshold Voltage	V <sub>FB</sub> Falling	0.556	V <sub>FB</sub> ×0.90	0.604	V
V <sub>FBUVD2</sub>	FB FIII OVD TITIESTIOID VOItage	V <sub>FB</sub> Rising	0.574	V <sub>FB</sub> ×0.93	0.628	V
gm (EA)	Trans Conductance Amplifier	COMP = 1.5 V	0.35	1	1.55	mS

All test items listed under Electrical Characteristics are done under the pulse load condition ( $Tj \approx Ta = 25$ °C).

## **APPLICATION INFORMAITON**



R1272SxxxA Typical Application Circuit at 500 kHz

# R1272S032A033-0500 Recommended External Components<sup>(1)</sup>

CP1 [μF]	LP [μH]	CP2 [μF]	Q1(FET)	Q2(FET)	L [μH]	CIN1 [μF]	CIN2 [μF]
10	1.0	10	_	_	2.2	10	10
CVIN	COUT 1 [μF]	COUT2 [μF]	CBST [μF]	CVCC [μF]	CCSS [nF]	CSPD [pF]	CC1 [nF]
OPEN	100	22*2	0.22	2.2	3.3	100	6.8
CC2 [pF]	RTOP1 [kΩ]	RBOT1 [kΩ]	RC [kΩ]	RRT [kΩ]	RS	RSEN [mΩ]	RSEN2 [kΩ]
47	91.43	22	12	68	OPEN	3	1

RCE [Ω] 0

<sup>(1)</sup> The bill of materials will be attached on the shipment of each purchased evaluation board.

#### **TECHNICAL NOTES**

The performance of power source circuits using this IC largely depends on peripheral circuits. When selecting the peripheral components, please consider the conditions of use. Do not allow each component, PCB pattern or the IC to exceed their respected rated values (voltage, current, and power) when designing the peripheral circuits.

- External components must be connected as close as possible to the Ics and make wiring as short as
  possible. Especially, the capacitor connected in between VIN pin and GND pin must be wiring the
  shortest. If their impedance is high, internal voltage of the IC may shift by the switching current, and the
  operating may be unstable. Make the power supply and GND lines sufficient.
- Place a capacitor (Cout) to keep a distance between C<sub>IN</sub> and Cout in order to avoid the high-frequency noise by input.
- AGND and PGND for the controller must be wired to the GND line at the low impedance point of the same layer with C<sub>IN</sub> and C<sub>OUT</sub>.
- Place a capacitor (C<sub>BST</sub>) as close as possible to the LX pin and the BST pin. If controlling slew rate for EMI, a resistor (R<sub>BST</sub>) should be in series between the BST pin and the capacitor (C<sub>BST</sub>), but not be in series to FET for HGATE and LGATE pins. Because connecting the resistor in series to the FET becomes a cause of a through-current.
- The tab on the bottom of the HSOP-18 package must be connected to GND when mounted on the board. To improve thermal dissipation on the multilayer board, set via to release the heat to the other layer in the connecting part of the tab on the bottom. Likewise, thermal dissipation for FET is required.
- The MODE pin requires the H / L voltages with the high stability when the forced PWM mode (MODE = "H") or the VFM mode (MODE = "L") is enabled. If the voltage with the high stability cannot be applied, connection to the VCC pin as "H" level or the AGND pin as "L" level is recommended. If connecting to the PGND pin as noisy, a malfunction may occur. Avoid the use of the MODE pin being "Open".
- If V<sub>OUT</sub> is a minus potential, the setup cannot occur.
- The power for the controller and for the high-side FET must be used on the same power supply, since the internal slope compensation is applied as the power supply voltage of the high-side FET is equal to the controller's. If applying the other power supply voltage, the controller will become unstable owing to the inappropriate slope compensation.



- The products and the product specifications described in this document are subject to change or discontinuation of production without notice for reasons such as improvement. Therefore, before deciding to use the products, please refer to our sales representatives for the latest information thereon.
- 2. The materials in this document may not be copied or otherwise reproduced in whole or in part without prior written consent of our company.
- 3. Please be sure to take any necessary formalities under relevant laws or regulations before exporting or otherwise taking out of your country the products or the technical information described herein.
- 4. The technical information described in this document shows typical characteristics of and example application circuits for the products. The release of such information is not to be construed as a warranty of or a grant of license under our company's or any third party's intellectual property rights or any other rights.
- 5. The products listed in this document are intended and designed for use as general electronic components in standard applications (office equipment, telecommunication equipment, measuring instruments, consumer electronic products, amusement equipment etc.). Those customers intending to use a product in an application requiring extreme quality and reliability, for example, in a highly specific application where the failure or misoperation of the product could result in human injury or death (aircraft, spacevehicle, nuclear reactor control system, traffic control system, automotive and transportation equipment, combustion equipment, safety devices, life support system etc.) should first contact us.
- 6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
- 7. Anti-radiation design is not implemented in the products described in this document.
- 8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
- 9. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
- 10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.
- 11. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



#### Nisshinbo Micro Devices Inc.

Official website

https://www.nisshinbo-microdevices.co.jp/en/

**Purchase information** 

https://www.nisshinbo-microdevices.co.jp/en/buy/